

Atomically precise surface and interface engineering via atomic layer deposition to enable high-performance materials, detectors, and instruments

F. Greer, M.E. Hoenk, T.J. Jones, B.C. Jacquot, M. Dickie, S. Monacos, and S. Nikzad P. Day and R. Leduc

Jet Propulsion Laboratory/California Institute of Technology

E. Hamden and D. Schiminovich,

Columbia University

M. Beasley, B. Gantner, University of Colorado
Patrick Morrissey, Christopher Martin
California Institute of Technology
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Outline

- Description of Technology
- Overview of Application Results
 - Anti-reflective coatings
 - Optical elements (filters)
 - Superconducting detectors
 - Surface treatments
- Conclusions/Future
 - Surface passivation



JPL's Oxford ALD System

Acknowledgements:

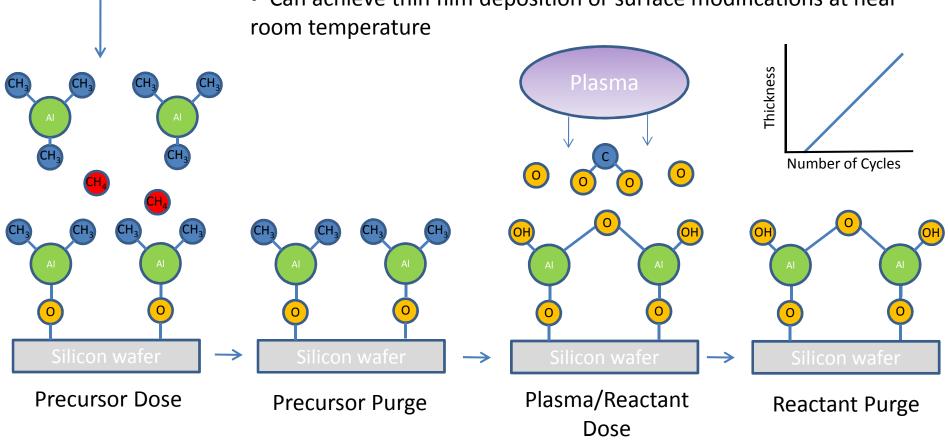
Novellus Systems (iALD group: F. Greer et al.)



Initial Surface

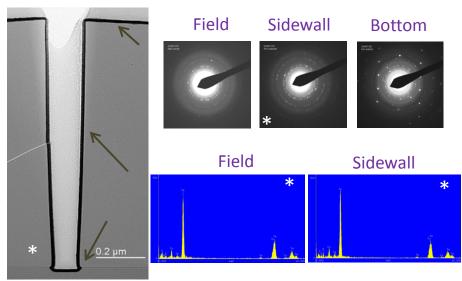
Atomic Layer Deposition Fundamentals

- Surface reaction mediated deposition
- ALD cycles are repeated until desired film thickness is achieved
- Metals, Nitrides, and Oxides are achieved through choice of precursor and reactant species
- Can achieve thin film deposition or surface modifications at near

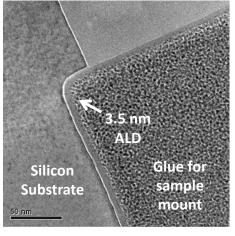


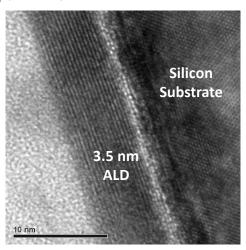


Properties and Advantages of ALD



TEM images of ultra-thin TiO₂ (3.5nm), conformal ALD film





Selective Area Diffraction and EDS show uniform film properties throughout high aspect ratio features

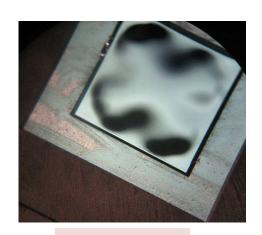
KNI TEM of a JPL ALD film (image credit Carol Garland/Bophan Chhim)

- Atomic Layer Deposition is inherently 100% conformal up to very high aspect ratios
- Film properties and composition are uniform throughout aggressive features
- Film properties and composition are uniform across arbitrarily large substrates

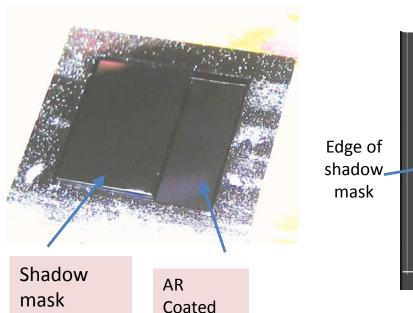
^{*} F.Greer, et al. iALD TaN film, Novellus Systems, AVS-ALD Conference 2005

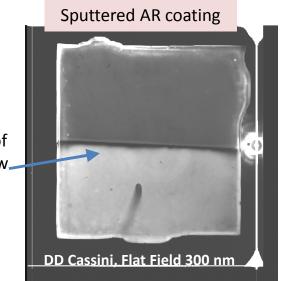
Anti-Reflective Coatings for UV Astronomy





12um thick Membrane is unsupported





- AR Coatings used to enhance quantum efficiency of silicon detectors.
 - Index of refraction of silicon changes significantly in the UV, requiring multiple materials for optimal performance
 - Thin films required in UV (10-25nm)
 - Flat field illumination during test
 - Brighter → Higher QE
- Shadow masking used to ensure internal standard for comparison

Delta doping technology as the ideal Back Illumination solution

 $0.004 \mu m$

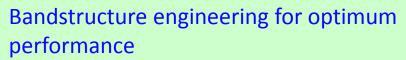


Delta-doped layer

(boron in single atomic layer)

original Si

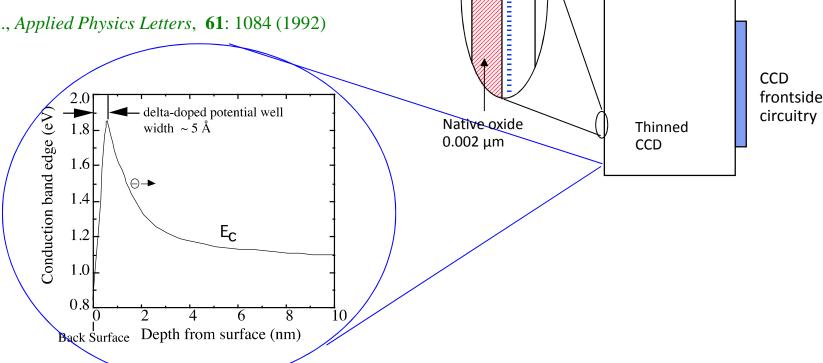
~ 15 µm



Atomic layer control over device structure

Low temperature process, compatible with VLSI, fully fabricated devices (CCDs, CMOS, PIN arrays)

Hoenk et al., Applied Physics Letters, 61: 1084 (1992)



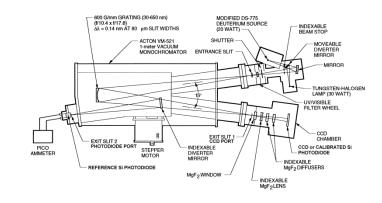
Fully-processed devices are modified using Si Molecular Beam Epitaxy (MBE)

S. Nikzad, 2011 Frank Greer 2011



CCD Characterization

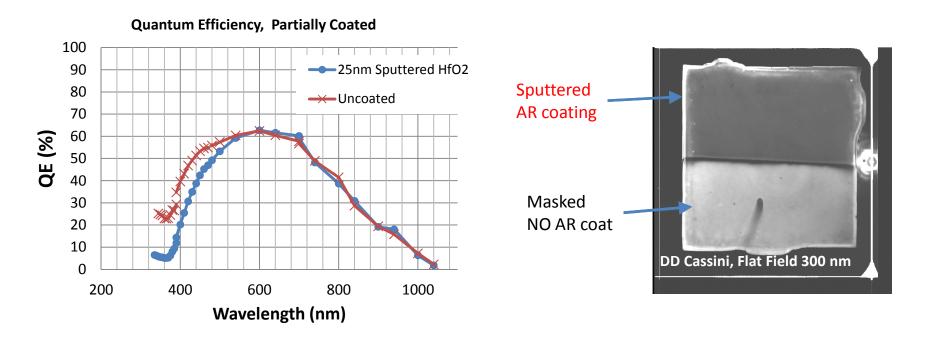
- Characterization of absolute quantum efficiency of detectors is very difficult in the UV
 - Atmospheric absorption occurs in wavelengths < 160nm
 - Silicon CCDs must be cooled to liquid nitrogen temperatures to reduce dark current
 - Quantum yield (electrons/photon) is greater that 1 for short wavelengths
- JPL has developed a system and methodology for these tests in our laboratory for rapid feedback during detector development and flight qualification*







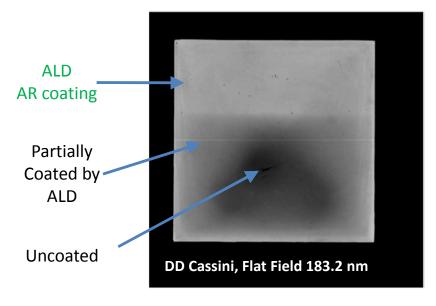
Sputtered anti-reflective coatings

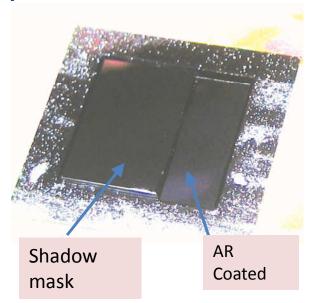


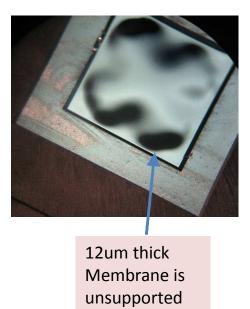
- Sputtered film QE far below that of uncoated reference. Effect also observed for sputtered MgO.
- Poor UV response of HfO₂ suggests AR coating problem is at the nanometer length scale



ALD AR Coating Experiments



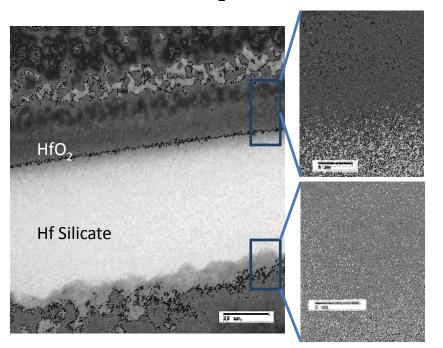




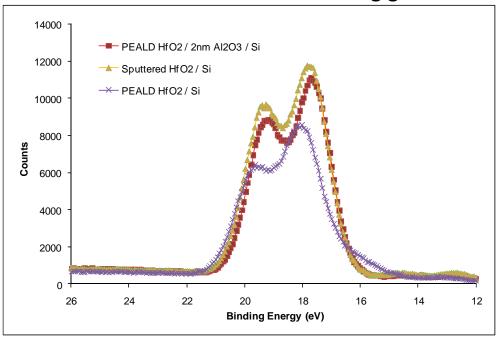
- Shadow masking is somewhat difficult due to conformality of the ALD coating process
 - Mask does not sit flat on unsupported membrane so partial coating is observed over most of CCD
- Aluminum oxide AR coating does improve UV response

Importance of Chemistry in ALD AR Coatings

TEM of PEALD HfO₂ directly on Si



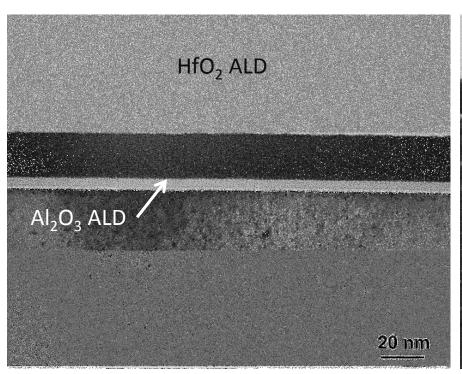
XPS Data from initial AR coating growth

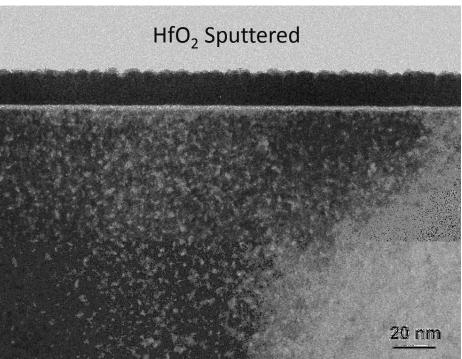


- ALD is a chemical process that occurs at elevated temperatures
 - Chemical interaction of ALD coating with substrate is possible.
 - Surface nucleation and reactions must be carefully considered
- ALD bilayers were utilized to successfully mitigate this effect

Comparison of Nanomorphology of AR Coatings





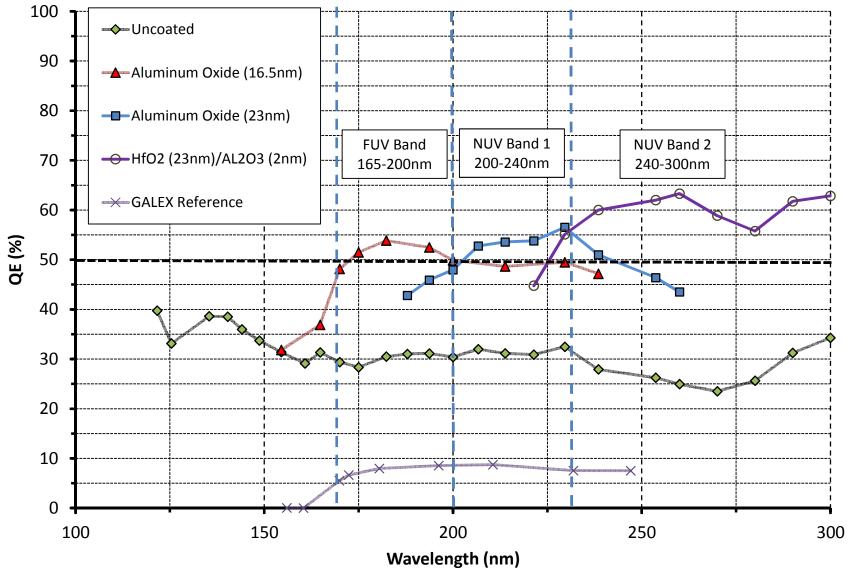


- Appearance of ALD AR coating stack (Left) is significantly better than the Sputtered AR coating (right)
 - ALD is more dense (darker in the image)
 - ALD is smoother (potentially less scatter)
- ALD AR coating technique allows for multilayers with sharp interfaces
 - Provides for optically transparent chemical barriers between films (Al₂O₃ film at left)
- ALD AR coating technique has atomic layer precision
 - Enables sub-nanometer control over film thickness, which is important for UV AR coatings as
 <2nm thickness change impacts the performance

QE of FUV-NUV Bands

NASA

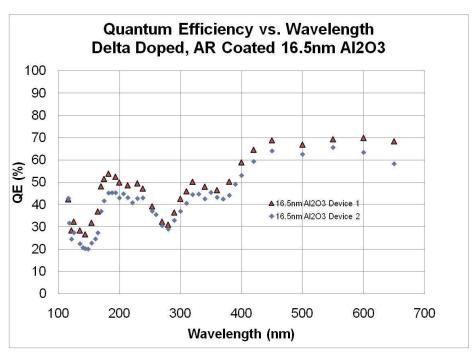
Delta Doped, Partial ALD AR Coatings



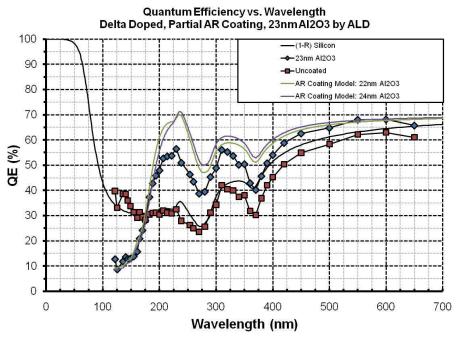
Atomic Layer Deposition AR coatings provide up to **2X improvement** over uncoated baseline and **5x improvement** over incumbent UV detector technology



ALD Enables Atomic Control of Coatings



Same exact recipe run on JPL ALD system on two different devices separated by **a month**

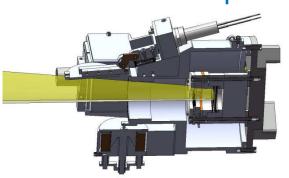


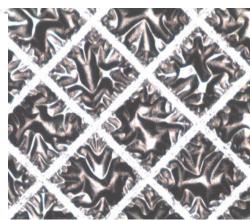
Wavelength dependence of coating performance *correctly predicted* by AR coating models based on precision UV ellipsometry measurements

- Reproducibility and accuracy of the ALD technique enables rational design and fabrication of anti-reflective coatings at the nanometer scale
- Multilayers feasible when required to prevent interactions or to provide for integrated filters (e.g. bandpass)

UV Filter Enhancement/Fabrication

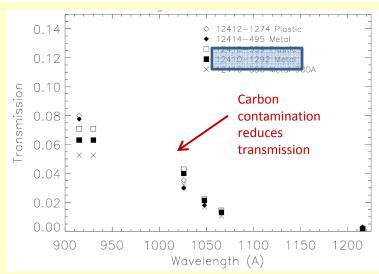
FIRE telescope

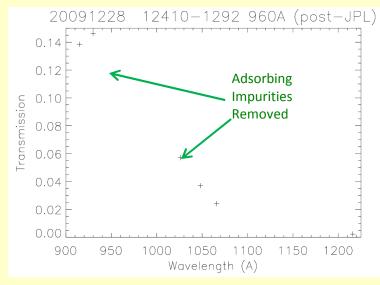




Indium foil on Ni mesh

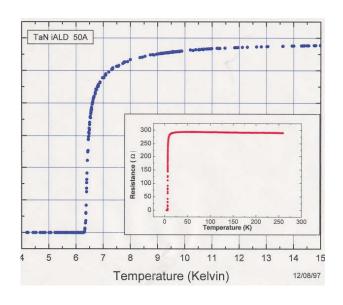
- FIRE Telescope objective to image the very hottest stars, with no interference from Lyman alpha
 - Thin Indium Foil (0.1um thick) supported by Ni mesh acts as UV filter cutting off transmission above 1100A
- •JPL post treatments yielded improvement in filter transmission
- •AR coatings results demonstrate that ALD can be applied to live devices
- •Thus, ALD, with appropriate interfacial layers, can be used to monolithically integrate filters into detector elements

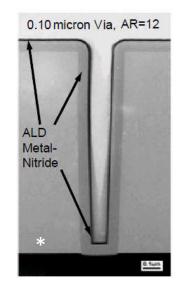




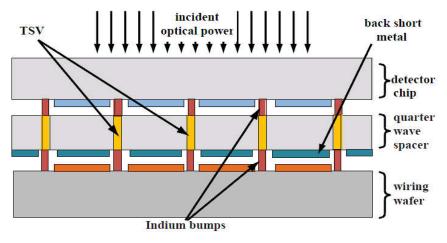


Superconducting Detectors for Submillimeter Astronomy

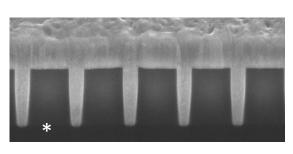




- ALD TiN, TaN, and NbN films are all superconducting
- Enables *uniform* production of superconducting detector arrays across *8" wafers*.
- Enables *3D integration* of arrays for *hybrid, buttable* detectors



Electroplated array of vias using 100A of ALD as barrier/seed



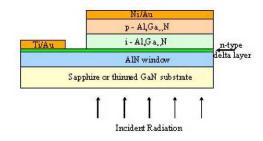




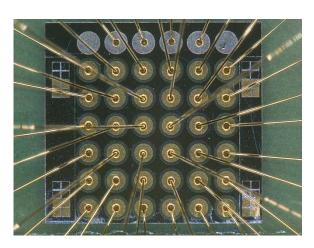
ALD for III-N Detectors

•Exploring ALD as a means to reduce dark current in III-N APD UV detectors.

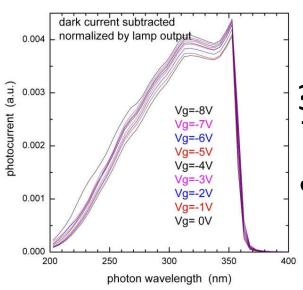
III-N Mesa Structure



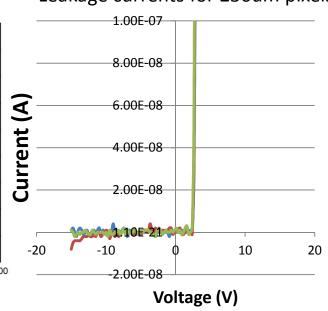
6x6 250um pixel QE test array



Responsivity for different biases



Leakage currents for 250um pixels



Frank Greer 2011



Conclusions

- Benefits of ALD and Plasma Treatments
 - Ultrathin, highly conformal, and uniform films over arbitrarily large surface area
 - High quality films (density, roughness, conductivity, etc.)
 - Angstrom level control of stochiometry, interfaces, and surface properties
 - Multilayer nanolaminates/nanocomposites
 - Low temperature surface engineering

Applications

- Anti-reflective coatings/Mirrors/Filters/Optics for UV/Vis/NIR Detectors
- Superconducting Detectors
- Surface Passivation



Acknowledgements

- APRA
- JPL R&TD Funding